

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC8101xxxxGR-G
Typical Mass: 3 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.228	Silicon	76100	7440-21-3
		- Arsenic	4	7440-38-2
Lead pad	0.558	Nickel	185900	7440-02-0
		Silver	14900	7440-22-4
		Gold	2700	7440-57-5
Die attach	0.013	Epoxy Resin	4500	—
		Silica	3400	60676-86-0
Bonding wire	0.030	Gold	10100	7440-57-5
Resin	1.864	Silica	621200	60676-86-0
		Silica (crystal)	14200	14808-60-7
		Epoxy Resin	35200	—
		Phenol Resin	21100	—
		Metal Hydroxide	10700	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."